

**Features:**

- n Isolated mounting base 3000V~
- n Solder joint technology with increased power cycling capability
- n Space and weight saving

Typical Applications:

- n AC/DC Motor drives
- n Various rectifiers
- n DC supply for PWM inverter

V _{DRM} , V _{R_{RRM}}	Type & Outline
600V	MTC200-06-229H3/229H3B
800V	MTC200-08-229H3/229H3B
1000V	MTC200-10-229H3/229H3B
1200V	MTC200-12-229H3/229H3B
1400V	MTC200-14-229H3/229H3B
1600V	MTC200-16-229H3/229H3B
1800V	MTC200-18-229H3/229H3B

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T _j (°C)	VALUE			UNIT
				Min	Type	Max	
I _{T(AV)}	Mean on-state current	180° half sine wave 50Hz Single side cooled, T _c =85°C	125			200	A
I _{T(RMS)}	RMS on-state current		125			314	A
I _{DRM} I _{R_{RRM}}	Repetitive peak current	at V _{DRM} at V _{R_{RRM}}	125			40	mA
I _{TSM}	Surge on-state current	10ms half sine wave	125			4.0	kA
I ² t	I ² t for fusing coordination	V _R =60%V _{R_{RRM}}				80	A ² s*10 ³
V _{TO}	Threshold voltage		125			0.70	V
r _r	On-state slope resistance					1.11	mΩ
V _{TM}	Peak on-state voltage	I _{TM} =600A	25			1.80	V
dv/dt	Critical rate of rise of off-state voltage	V _{DM} =67%V _{DRM}	125			1000	V/μs
di/dt	Critical rate of rise of on-state current	Gate source 1.5A t _r ≤0.5μs Repetitive	125			200	A/μs
I _{GT}	Gate trigger current	V _A =12V, I _A =1A	25	30		200	mA
V _{GT}	Gate trigger voltage			0.6		2.5	V
I _H	Holding current			10		250	mA
I _L	Latching current					1000	mA
V _{GD}	Non-trigger gate voltage	V _{DM} =67%V _{DRM}	125			0.2	V
R _{th(j-c)}	Thermal resistance Junction to case	Single side cooled per chip				0.16	°C/W
R _{th(c-h)}	Thermal resistance case to heatsink	Single side cooled per chip				0.08	°C/W
V _{iso}	Isolation voltage	50Hz, R.M.S, t=1min, I _{iso} :1mA(MAX)		3000			V
F _m	Terminal connection torque(M6)			2.5		4.0	N·m
	Mounting torque(M6)			4.5		6.0	N·m
T _{vj}	Junction temperature			-40		125	°C
T _{stg}	Stored temperature			-40		125	°C
W _t	Weight				165		g
Outline	229H3、229H3B						

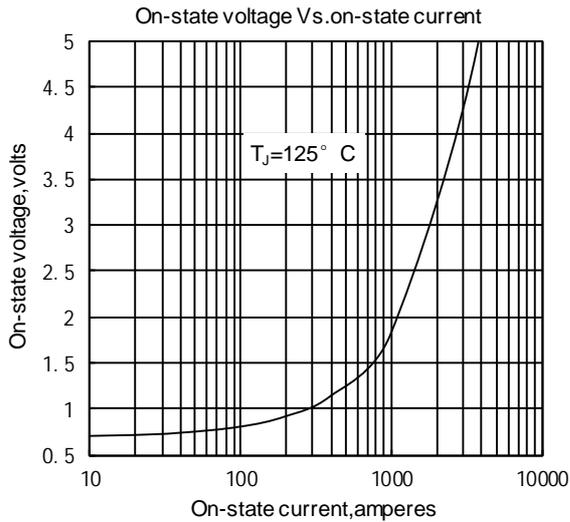


Fig.1

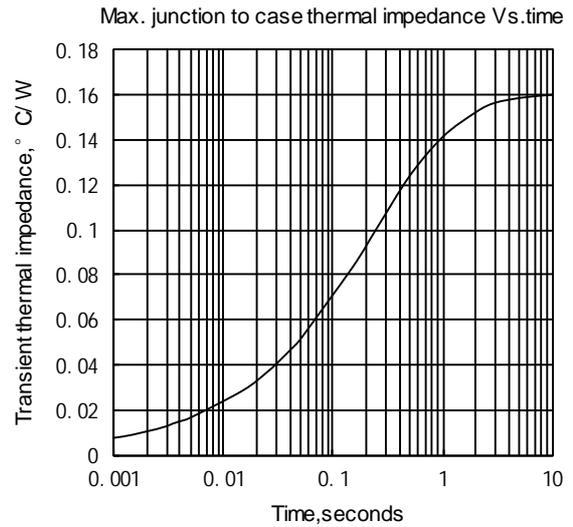


Fig.2

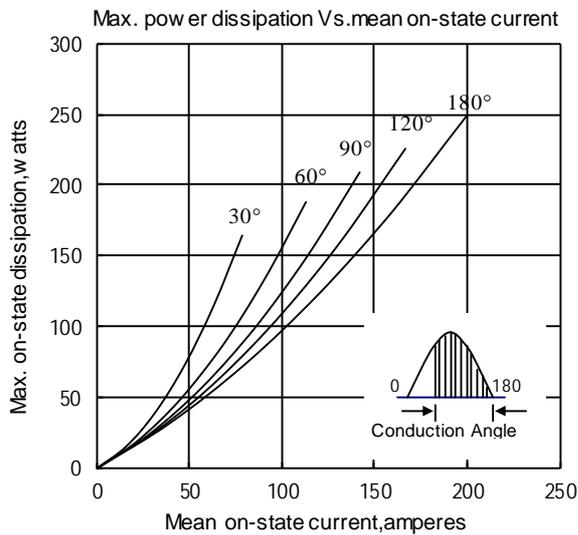


Fig.3

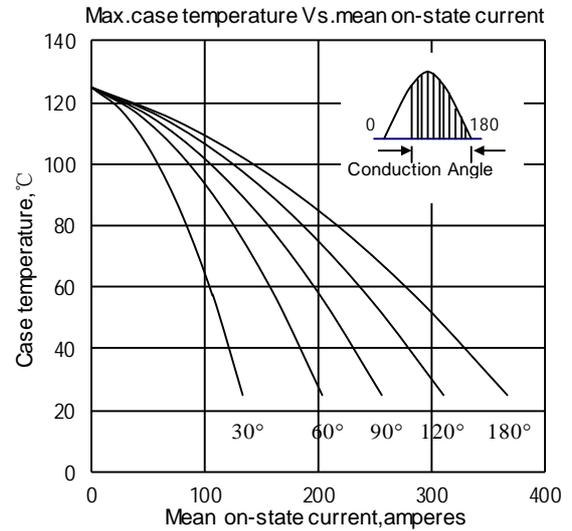


Fig.4

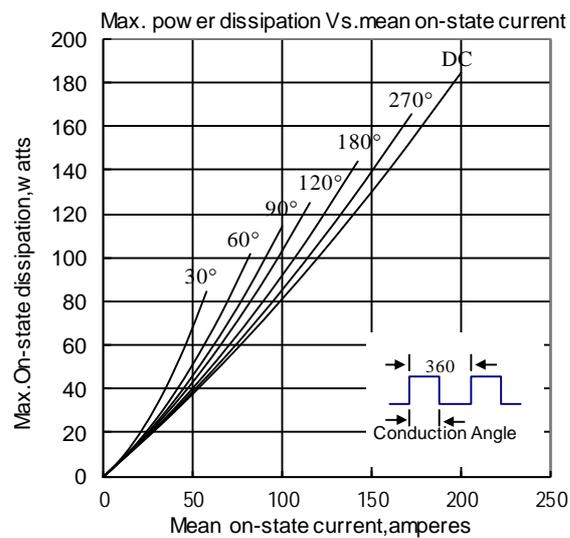


Fig.5

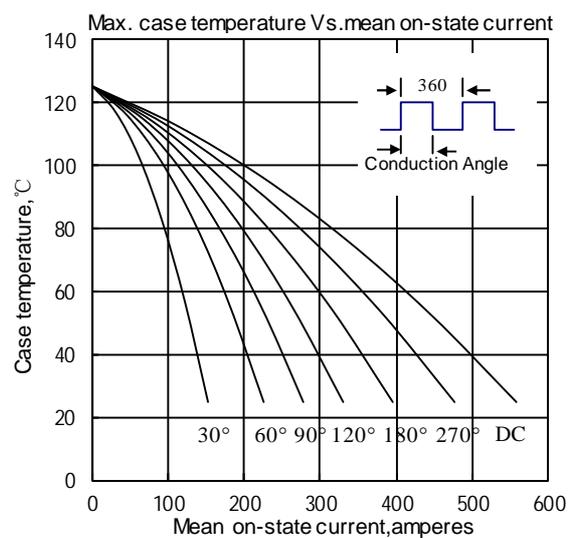


Fig.6

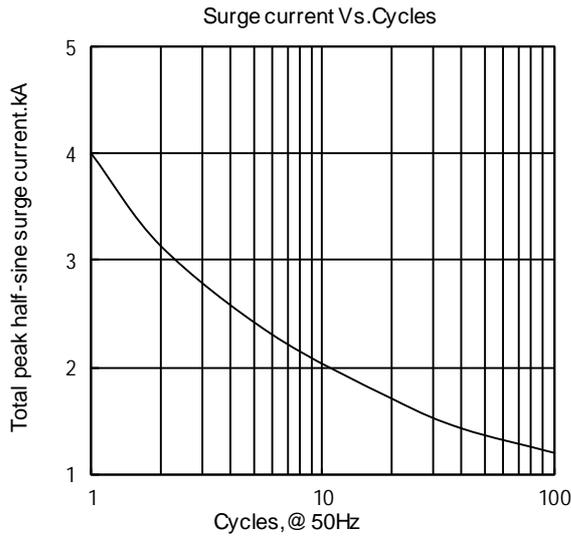


Fig.7

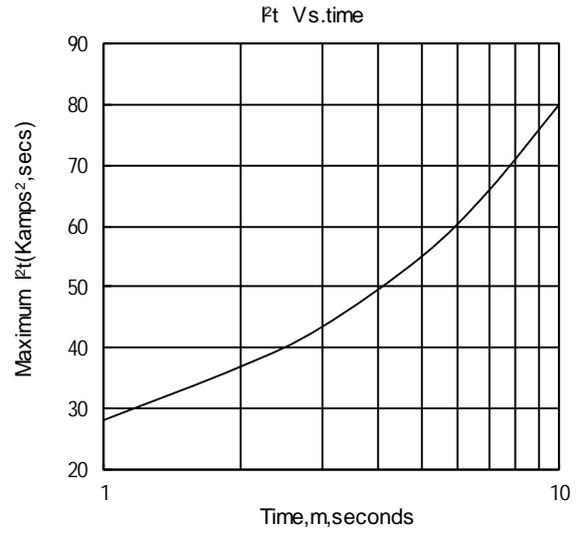


Fig.8

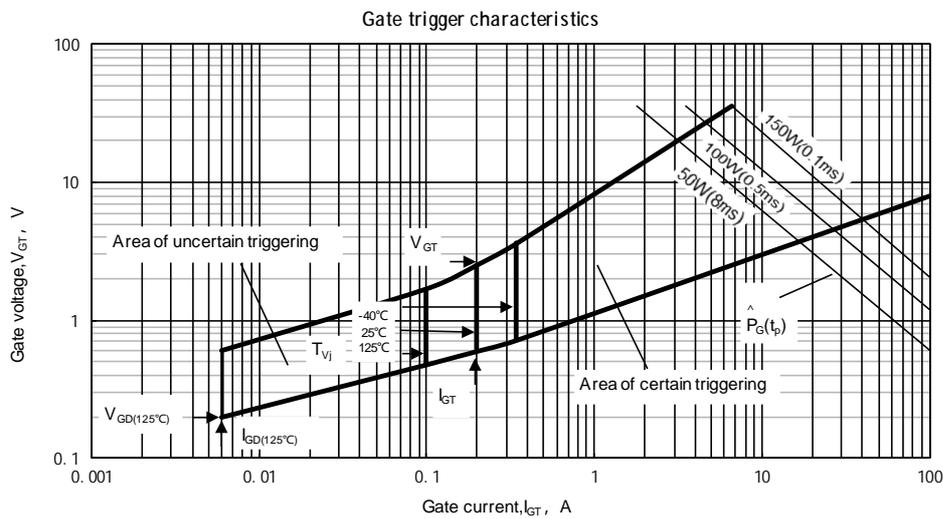
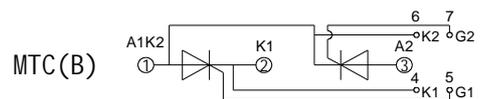
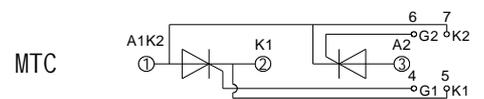
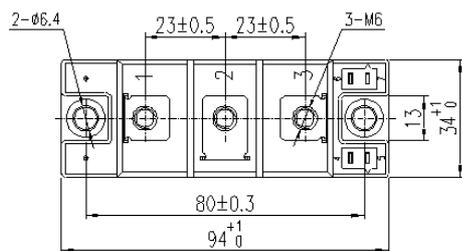
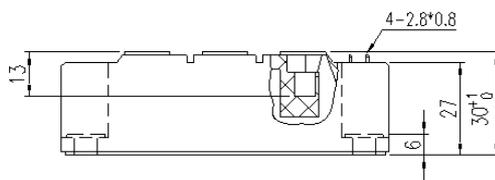


Fig.9

Outline:



Unmarked dimensional tolerance: ±0.5mm

TECHSEM reserves the right to change specifications without notice.